

74AUP2GU04

Low-power dual unbuffered inverter

Rev. 5 — 11 October 2013

Product data sheet

1. General description

The 74AUP2GU04 provides two unbuffered inverting gates.

This device ensures a very low static and dynamic power consumption across the entire V_{CC} range from 0.8 V to 3.6 V.

2. Features and benefits

- Wide supply voltage range from 0.8 V to 3.6 V
- High noise immunity
- ESD protection:
 - ◆ HBM JESD22-A114F Class 3A exceeds 5000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
 - ◆ CDM JESD22-C101E exceeds 1000 V
- Low static power consumption; $I_{CC} = 0.9 \mu A$ (maximum)
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- Inputs accept voltages up to 3.6 V
- Multiple package options
- Specified from $-40^{\circ}C$ to $+85^{\circ}C$ and $-40^{\circ}C$ to $+125^{\circ}C$

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74AUP2GU04GW	$-40^{\circ}C$ to $+125^{\circ}C$	SC-88	plastic surface-mounted package; 6 leads	SOT363
74AUP2GU04GM	$-40^{\circ}C$ to $+125^{\circ}C$	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body $1 \times 1.45 \times 0.5$ mm	SOT886
74AUP2GU04GF	$-40^{\circ}C$ to $+125^{\circ}C$	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body $1 \times 1 \times 0.5$ mm	SOT891
74AUP2GU04GN	$-40^{\circ}C$ to $+125^{\circ}C$	XSON6	extremely thin small outline package; no leads; 6 terminals; body $0.9 \times 1.0 \times 0.35$ mm	SOT1115
74AUP2GU04GS	$-40^{\circ}C$ to $+125^{\circ}C$	XSON6	extremely thin small outline package; no leads; 6 terminals; body $1.0 \times 1.0 \times 0.35$ mm	SOT1202



4. Marking

Table 2. Marking

Type number	Marking code ^[1]
74AUP2GU04GW	aD
74AUP2GU04GM	aD
74AUP2GU04GF	aD
74AUP2GU04GN	aD
74AUP2GU04GS	aD

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram

Fig 1. Logic symbol

Fig 2. IEC logic symbol

Fig 3. Logic diagram (one gate)

6. Pinning information

6.1 Pinning

Fig 4. Pin configuration SOT363

Fig 5. Pin configuration SOT886

Fig 6. Pin configuration SOT891, SOT1115 and SOT1202

6.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
1A	1	data input
GND	2	ground (0 V)
2A	3	data input
2Y	4	data output
V _{CC}	5	supply voltage
1Y	6	data output

7. Functional description

Table 4. Function table^[1]

Input	Output
nA	nY
L	H
H	L

- [1] H = HIGH voltage level;
L = LOW voltage level.

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+4.6	V
I _{IK}	input clamping current	V _I < 0 V	-50	-	mA
V _I	input voltage		^[1] -0.5	+4.6	V
I _{OK}	output clamping current	V _O < 0 V	-50	-	mA
V _O	output voltage		^[2] -0.5	V _{CC} + 0.5	V
I _O	output current	V _O = 0 V to V _{CC}	-	±20	mA
I _{CC}	supply current		-	50	mA
I _{GND}	ground current		-50	-	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	T _{amb} = -40 °C to +125 °C	^[3] -	250	mW

- [1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

- [2] The output voltage ratings may be exceeded if the output current ratings are observed.

- [3] For SC-88 packages: above 87.5 °C the value of P_{tot} derates linearly with 4.0 mW/K.
For XSON6 packages: above 118 °C the value of P_{tot} derates linearly with 7.8 mW/K.

9. Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		0.8	3.6	V
V_I	input voltage		0	3.6	V
V_O	output voltage		0	V_{CC}	V
T_{amb}	ambient temperature		-40	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 0.8\text{ V to }3.6\text{ V}$	0	200	ns/V

10. Static characteristics

Table 7. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$T_{amb} = 25\text{ °C}$						
V_{IH}	HIGH-level input voltage	$V_{CC} = 0.8\text{ V to }3.6\text{ V}$	$0.75 \times V_{CC}$	-	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 0.8\text{ V to }3.6\text{ V}$	-	-	$0.25 \times V_{CC}$	V
V_{OH}	HIGH-level output voltage	$V_I = \text{GND or } V_{CC}$				
		$I_O = -20\text{ }\mu\text{A}; V_{CC} = 0.8\text{ V to }3.6\text{ V}$	$V_{CC} - 0.1$	-	-	V
		$I_O = -1.1\text{ mA}; V_{CC} = 1.1\text{ V}$	$0.75 \times V_{CC}$	-	-	V
		$I_O = -1.7\text{ mA}; V_{CC} = 1.4\text{ V}$	1.11	-	-	V
		$I_O = -1.9\text{ mA}; V_{CC} = 1.65\text{ V}$	1.32	-	-	V
		$I_O = -2.3\text{ mA}; V_{CC} = 2.3\text{ V}$	2.05	-	-	V
		$I_O = -3.1\text{ mA}; V_{CC} = 2.3\text{ V}$	1.9	-	-	V
		$I_O = -2.7\text{ mA}; V_{CC} = 3.0\text{ V}$	2.72	-	-	V
		$I_O = -4.0\text{ mA}; V_{CC} = 3.0\text{ V}$	2.6	-	-	V
V_{OL}	LOW-level output voltage	$V_I = \text{GND or } V_{CC}$				
		$I_O = 20\text{ }\mu\text{A}; V_{CC} = 0.8\text{ V to }3.6\text{ V}$	-	-	0.1	V
		$I_O = 1.1\text{ mA}; V_{CC} = 1.1\text{ V}$	-	-	$0.3 \times V_{CC}$	V
		$I_O = 1.7\text{ mA}; V_{CC} = 1.4\text{ V}$	-	-	0.31	V
		$I_O = 1.9\text{ mA}; V_{CC} = 1.65\text{ V}$	-	-	0.31	V
		$I_O = 2.3\text{ mA}; V_{CC} = 2.3\text{ V}$	-	-	0.31	V
		$I_O = 3.1\text{ mA}; V_{CC} = 2.3\text{ V}$	-	-	0.44	V
		$I_O = 2.7\text{ mA}; V_{CC} = 3.0\text{ V}$	-	-	0.31	V
		$I_O = 4.0\text{ mA}; V_{CC} = 3.0\text{ V}$	-	-	0.44	V
I_I	input leakage current	$V_I = \text{GND to } 3.6\text{ V}; V_{CC} = 0\text{ V to }3.6\text{ V}$	-	-	± 0.1	μA
I_{CC}	supply current	$V_I = \text{GND or } V_{CC}; I_O = 0\text{ A}; V_{CC} = 0.8\text{ V to }3.6\text{ V}$	-	-	0.5	μA
C_I	input capacitance	$V_{CC} = 0\text{ V to }3.6\text{ V}; V_I = \text{GND or } V_{CC}$	-	1.5	-	pF
C_O	output capacitance	$V_O = \text{GND}; V_{CC} = 0\text{ V}$	-	1.8	-	pF

Table 7. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = -40 °C to +85 °C						
V _{IH}	HIGH-level input voltage	V _{CC} = 0.8 V to 3.6 V	0.75 × V _{CC}	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 0.8 V to 3.6 V	-	-	0.25 × V _{CC}	V
V _{OH}	HIGH-level output voltage	V _I = GND or V _{CC}				
		I _O = -20 µA; V _{CC} = 0.8 V to 3.6 V	V _{CC} - 0.1	-	-	V
		I _O = -1.1 mA; V _{CC} = 1.1 V	0.7 × V _{CC}	-	-	V
		I _O = -1.7 mA; V _{CC} = 1.4 V	1.03	-	-	V
		I _O = -1.9 mA; V _{CC} = 1.65 V	1.30	-	-	V
		I _O = -2.3 mA; V _{CC} = 2.3 V	1.97	-	-	V
		I _O = -3.1 mA; V _{CC} = 2.3 V	1.85	-	-	V
		I _O = -2.7 mA; V _{CC} = 3.0 V	2.67	-	-	V
		I _O = -4.0 mA; V _{CC} = 3.0 V	2.55	-	-	V
V _{OL}	LOW-level output voltage	V _I = GND or V _{CC}				
		I _O = 20 µA; V _{CC} = 0.8 V to 3.6 V	-	-	0.1	V
		I _O = 1.1 mA; V _{CC} = 1.1 V	-	-	0.3 × V _{CC}	V
		I _O = 1.7 mA; V _{CC} = 1.4 V	-	-	0.37	V
		I _O = 1.9 mA; V _{CC} = 1.65 V	-	-	0.35	V
		I _O = 2.3 mA; V _{CC} = 2.3 V	-	-	0.33	V
		I _O = 3.1 mA; V _{CC} = 2.3 V	-	-	0.45	V
		I _O = 2.7 mA; V _{CC} = 3.0 V	-	-	0.33	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.45	V
I _I	input leakage current	V _I = GND to 3.6 V; V _{CC} = 0 V to 3.6 V	-	-	±0.5	µA
I _{CC}	supply current	V _I = GND or V _{CC} ; I _O = 0 A; V _{CC} = 0.8 V to 3.6 V	-	-	0.9	µA
T_{amb} = -40 °C to +125 °C						
V _{IH}	HIGH-level input voltage	V _{CC} = 0.8 V to 3.6 V	0.75 × V _{CC}	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 0.8 V to 3.6 V	-	-	0.25 × V _{CC}	V
V _{OH}	HIGH-level output voltage	V _I = GND or V _{CC}				
		I _O = -20 µA; V _{CC} = 0.8 V to 3.6 V	V _{CC} - 0.11	-	-	V
		I _O = -1.1 mA; V _{CC} = 1.1 V	0.6 × V _{CC}	-	-	V
		I _O = -1.7 mA; V _{CC} = 1.4 V	0.93	-	-	V
		I _O = -1.9 mA; V _{CC} = 1.65 V	1.17	-	-	V
		I _O = -2.3 mA; V _{CC} = 2.3 V	1.77	-	-	V
		I _O = -3.1 mA; V _{CC} = 2.3 V	1.67	-	-	V
		I _O = -2.7 mA; V _{CC} = 3.0 V	2.40	-	-	V
		I _O = -4.0 mA; V _{CC} = 3.0 V	2.30	-	-	V

Table 7. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{OL}	LOW-level output voltage	V _I = GND or V _{CC}				
		I _O = 20 µA; V _{CC} = 0.8 V to 3.6 V	-	-	0.11	V
		I _O = 1.1 mA; V _{CC} = 1.1 V	-	-	0.33 × V _{CC}	V
		I _O = 1.7 mA; V _{CC} = 1.4 V	-	-	0.41	V
		I _O = 1.9 mA; V _{CC} = 1.65 V	-	-	0.39	V
		I _O = 2.3 mA; V _{CC} = 2.3 V	-	-	0.36	V
		I _O = 3.1 mA; V _{CC} = 2.3 V	-	-	0.50	V
		I _O = 2.7 mA; V _{CC} = 3.0 V	-	-	0.36	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.50	V
I _I	input leakage current	V _I = GND to 3.6 V; V _{CC} = 0 V to 3.6 V	-	-	±0.75	µA
I _{CC}	supply current	V _I = GND or V _{CC} ; I _O = 0 A; V _{CC} = 0.8 V to 3.6 V	-	-	1.4	µA

11. Dynamic characteristics

Table 8. Dynamic characteristicsVoltages are referenced to GND (ground = 0 V); for test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	25 °C			-40 °C to +125 °C			Unit
			Min	Typ ^[1]	Max	Min	Max (85 °C)	Max (125 °C)	

C_L = 5 pF

t _{pd}	propagation delay	nA to nY; see Figure 7 ^[2]							
		V _{CC} = 0.8 V	-	6.2	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	0.9	2.3	4.4	0.9	4.8	5.3	ns
		V _{CC} = 1.4 V to 1.6 V	0.7	1.7	3.1	0.6	3.4	3.8	ns
		V _{CC} = 1.65 V to 1.95 V	0.5	1.4	2.6	0.5	2.9	3.2	ns
		V _{CC} = 2.3 V to 2.7 V	0.4	1.1	2.0	0.4	2.3	2.6	ns
		V _{CC} = 3.0 V to 3.6 V	0.3	1.0	1.8	0.3	2.1	2.4	ns

C_L = 10 pF

t _{pd}	propagation delay	nA to nY; see Figure 7 ^[2]							
		V _{CC} = 0.8 V	-	9.6	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	1.2	3.1	6.1	1.2	6.8	7.5	ns
		V _{CC} = 1.4 V to 1.6 V	1.0	2.3	4.0	0.9	4.6	5.1	ns
		V _{CC} = 1.65 V to 1.95 V	0.8	1.9	3.3	0.7	3.8	4.2	ns
		V _{CC} = 2.3 V to 2.7 V	0.6	1.5	2.7	0.6	3.1	3.5	ns
		V _{CC} = 3.0 V to 3.6 V	0.5	1.3	2.4	0.5	2.7	3.0	ns

Table 8. Dynamic characteristics ...continuedVoltages are referenced to GND (ground = 0 V); for test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +125 °C			Unit
			Min	Typ ^[1]	Max	Min	Max (85 °C)	Max (125 °C)	
C _L = 15 pF									
t _{pd}	propagation delay	nA to nY; see Figure 7	[2]						
		V _{CC} = 0.8 V	-	13.0	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	1.6	3.8	7.9	1.4	8.8	9.7	ns
		V _{CC} = 1.4 V to 1.6 V	1.3	2.8	4.9	1.1	5.7	6.3	ns
		V _{CC} = 1.65 V to 1.95 V	1.0	2.3	4.0	0.9	4.7	5.2	ns
		V _{CC} = 2.3 V to 2.7 V	0.8	1.9	3.2	0.8	3.7	4.1	ns
		V _{CC} = 3.0 V to 3.6 V	0.7	1.6	2.9	0.7	3.3	3.7	ns
C _L = 30 pF									
t _{pd}	propagation delay	nA to nY; see Figure 7	[2]						
		V _{CC} = 0.8 V	-	23.2	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	2.4	6.0	13.1	2.2	14.8	16.3	ns
		V _{CC} = 1.4 V to 1.6 V	2.0	4.2	7.6	1.8	9.0	9.9	ns
		V _{CC} = 1.65 V to 1.95 V	1.7	3.6	6.1	1.5	7.2	8.0	ns
		V _{CC} = 2.3 V to 2.7 V	1.4	2.9	4.8	1.3	5.7	6.3	ns
		V _{CC} = 3.0 V to 3.6 V	1.2	2.5	4.3	1.1	5.1	5.7	ns
C _L = 5 pF, 10 pF, 15 pF and 30 pF									
C _{PD}	power dissipation capacitance	f _i = 1 MHz; V _I = GND to V _{CC}	[3][4]						
		V _{CC} = 0.8 V	-	1.1	-	-	-	-	pF
		V _{CC} = 1.1 V to 1.3 V	-	1.1	-	-	-	-	pF
		V _{CC} = 1.4 V to 1.6 V	-	1.3	-	-	-	-	pF
		V _{CC} = 1.65 V to 1.95 V	-	1.5	-	-	-	-	pF
		V _{CC} = 2.3 V to 2.7 V	-	3.0	-	-	-	-	pF
		V _{CC} = 3.0 V to 3.6 V	-	4.5	-	-	-	-	pF

[1] All typical values are measured at nominal V_{CC}.[2] t_{pd} is the same as t_{PLH} and t_{PHL}.

[3] All specified values are the average typical values over all stated loads.

[4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$
f_i = input frequency in MHz;f_o = output frequency in MHz;C_L = load capacitance in pF;V_{CC} = supply voltage in V;

N = number of inputs switching;

Σ(C_L × V_{CC}² × f_o) = sum of the outputs.

12. Waveforms

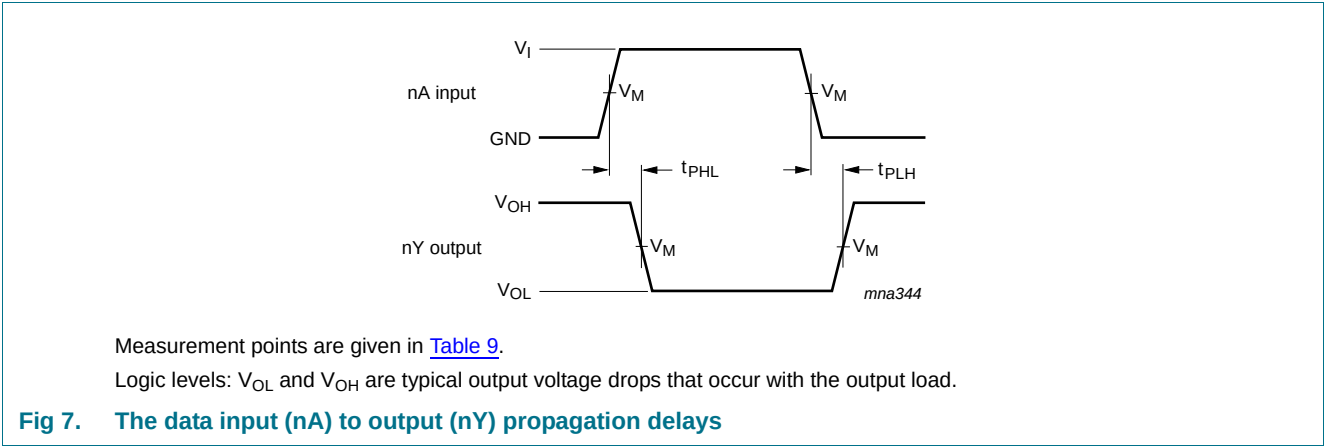


Table 9. Measurement points

Supply voltage	Output	Input		
V_{CC}	V_M	V_M	V_I	$t_r = t_f$
0.8 V to 3.6 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	V_{CC}	≤ 3.0 ns

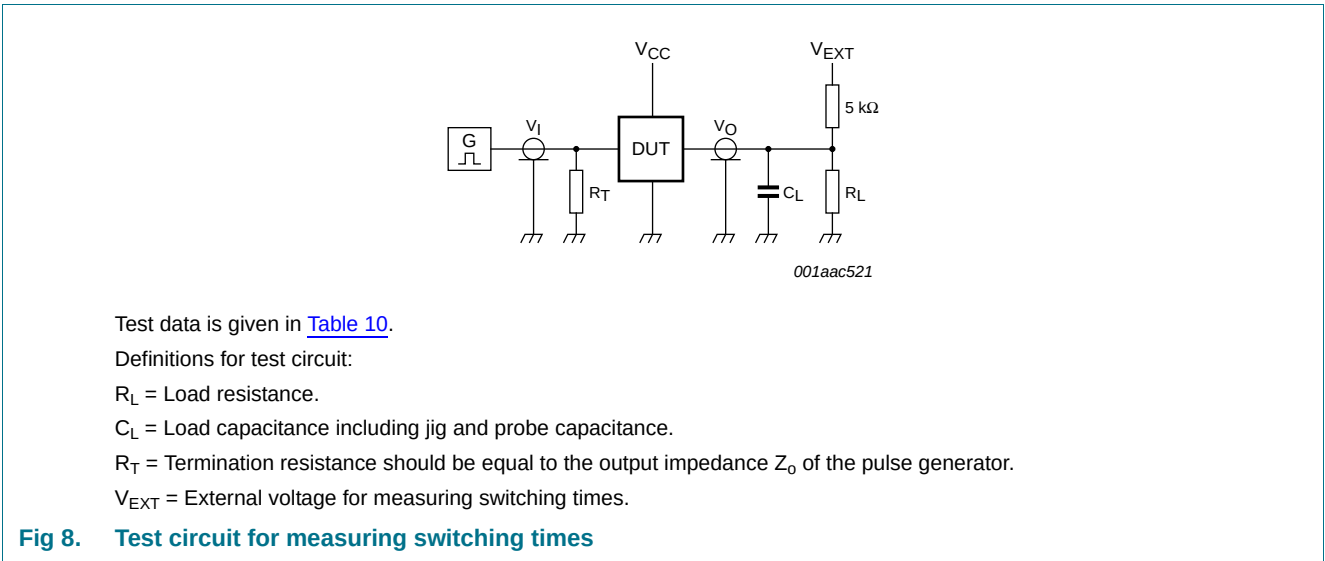
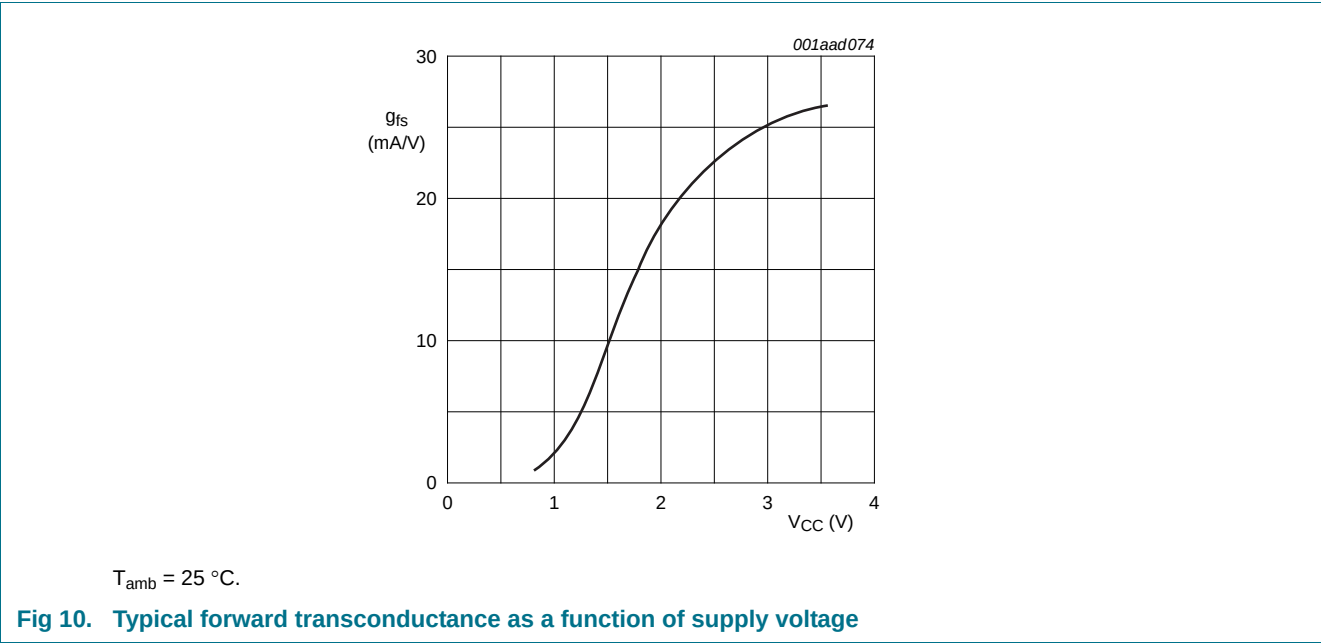
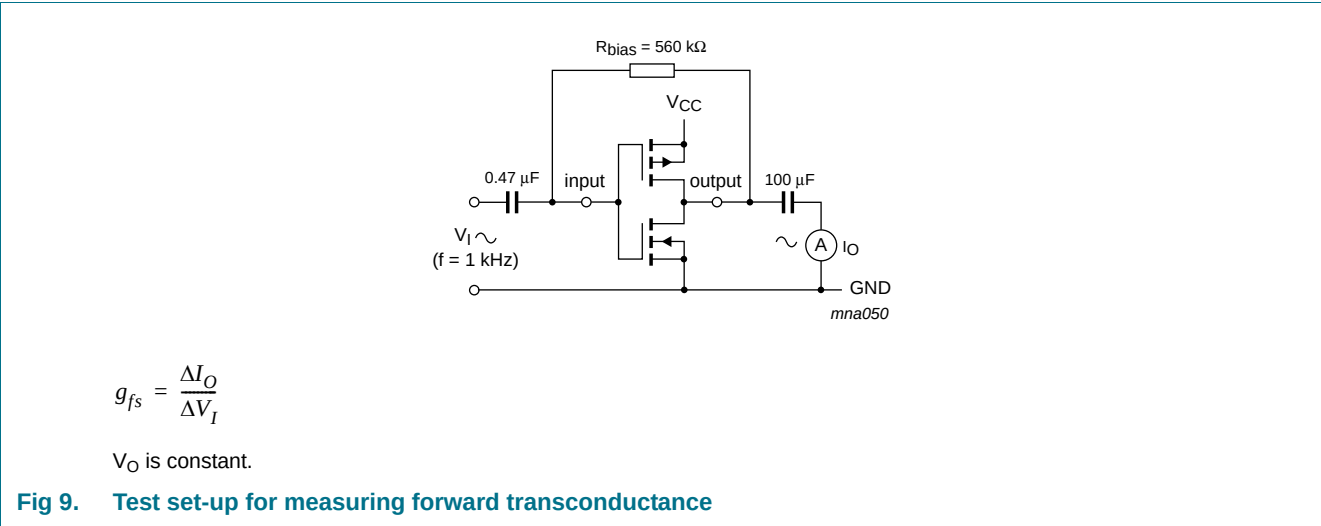


Table 10. Test data

Supply voltage	Load		V_{EXT}		
V_{CC}	C_L	R_L ^[1]	t_{PLH}, t_{PHL}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
0.8 V to 3.6 V	5 pF, 10 pF, 15 pF and 30 pF	5 kΩ or 1 MΩ	open	GND	$2 \times V_{CC}$

[1] For measuring enable and disable times $R_L = 5$ kΩ, for measuring propagation delays, set-up and hold times and pulse width $R_L = 1$ MΩ.

13. Additional characteristics

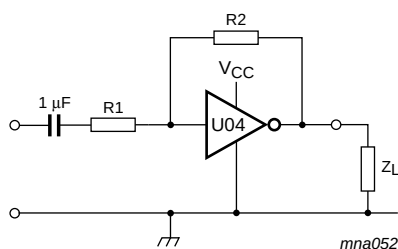


14. Application information

Some applications for the 74AUP2GU04 are:

- Linear amplifier (see [Figure 11](#))
- Crystal oscillator (see [Figure 12](#))

Remark: All values given are typical values unless otherwise specified.



$Z_L > 10 \text{ k}\Omega$.

$R1 \geq 3 \text{ k}\Omega$.

$R2 \leq 1 \text{ M}\Omega$.

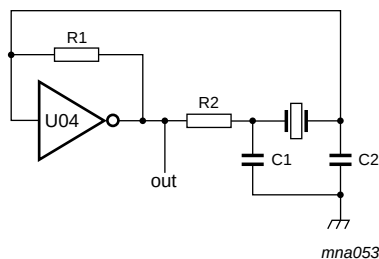
Open loop amplification: $A_{OL} = 20$.

$$\text{Voltage amplification: } A_V = -\frac{A_{OL}}{1 + \frac{R1}{R2}(1 + A_{OL})}$$

$V_{o(p-p)} = V_{CC} - 1.5 \text{ V}$ centered at $0.5 \times V_{CC}$.

Unity gain bandwidth product is 5 MHz.

Fig 11. Linear amplifier application



$C1 = 47 \text{ pF}$.

$C2 = 22 \text{ pF}$.

$R1 = 1 \text{ M}\Omega$ to $10 \text{ M}\Omega$.

$R2$ optimum value depends on the frequency and required stability against changes in V_{CC} or average minimum I_{CC} ($I_{CC} = 2 \text{ mA}$ at $V_{CC} = 3.3 \text{ V}$ and $f = 10 \text{ MHz}$).

Fig 12. Crystal oscillator application

15. Package outline

Plastic surface-mounted package; 6 leads

SOT363

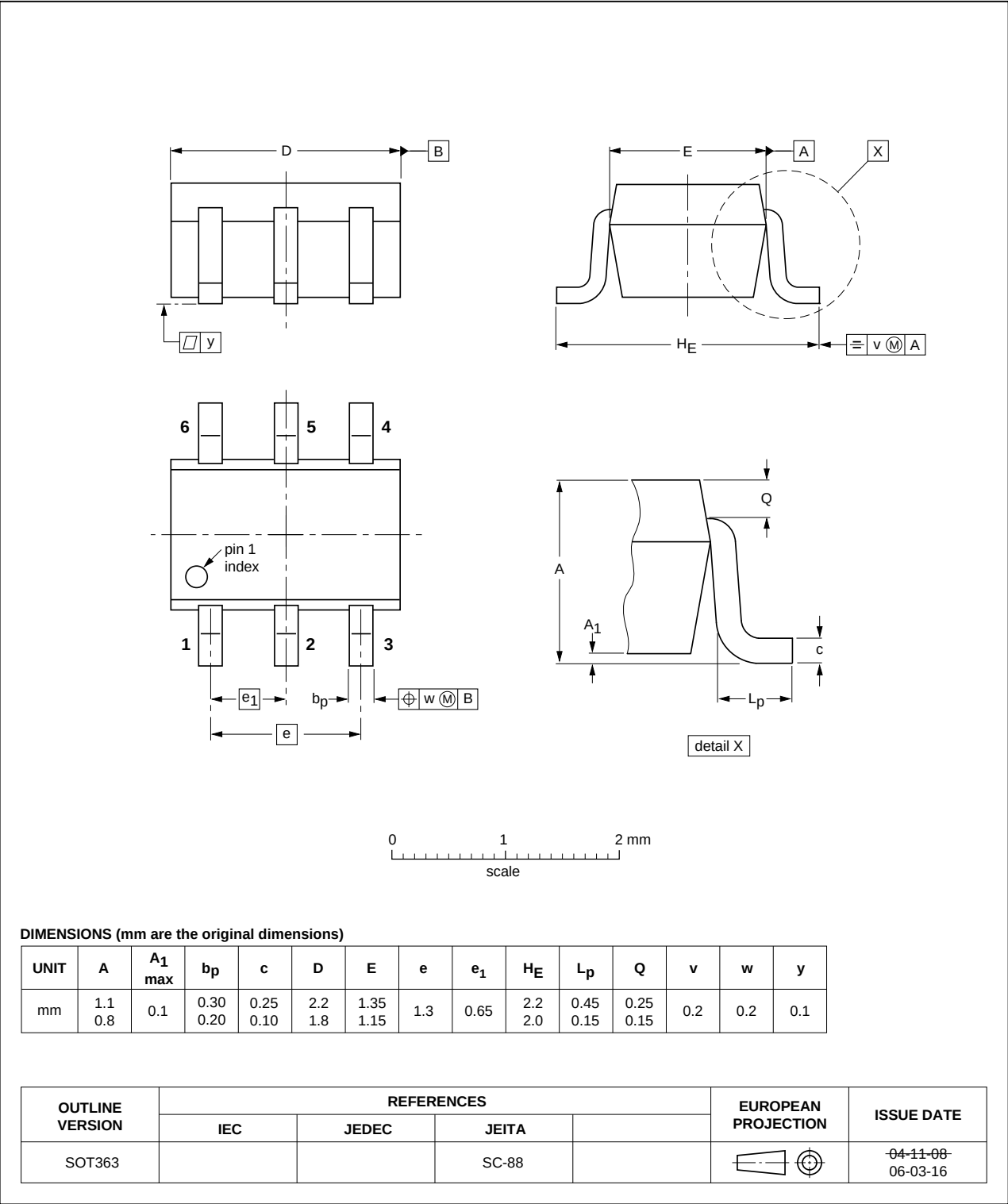


Fig 13. Package outline SOT363 (SC-88)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886

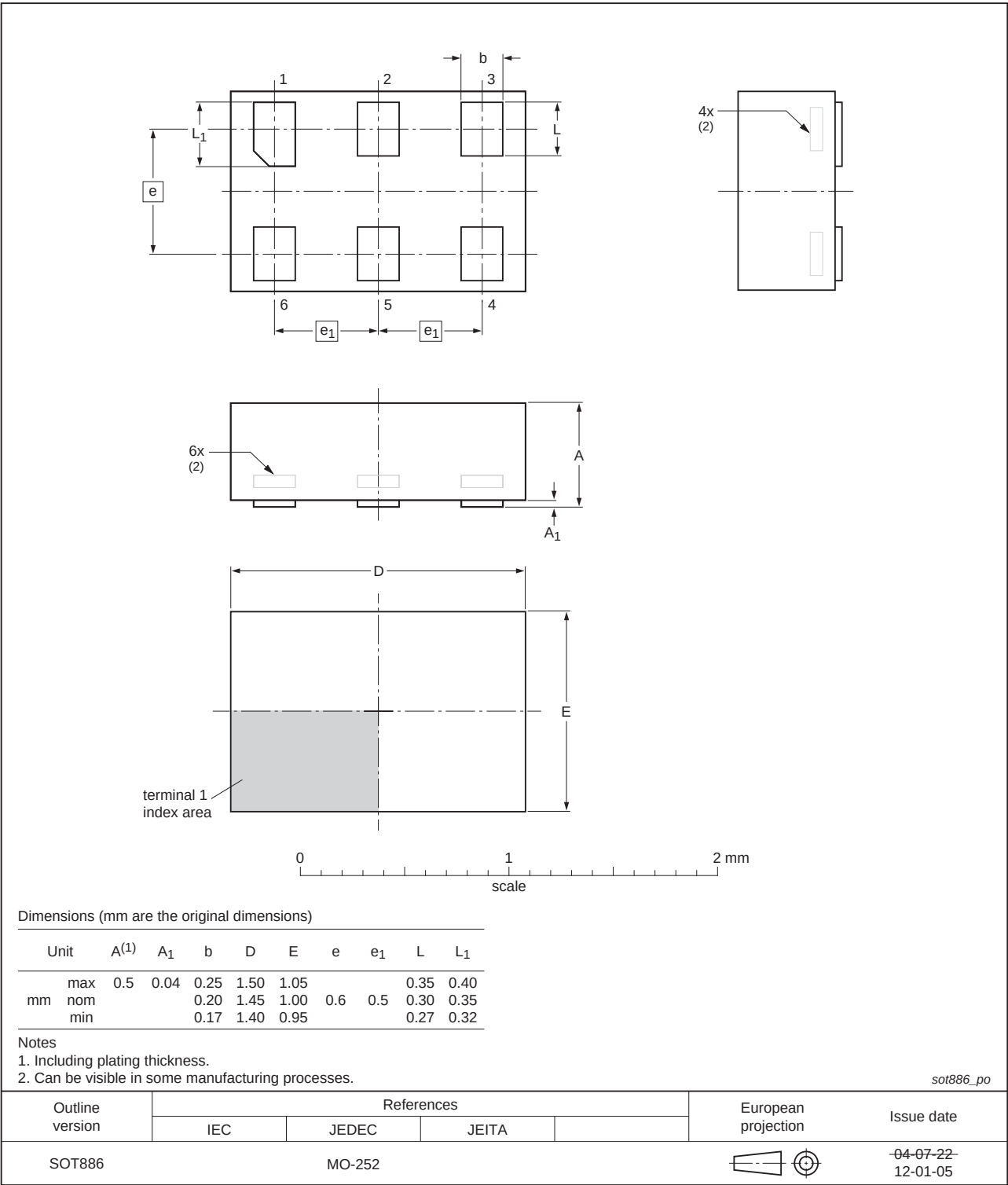


Fig 14. Package outline SOT886 (XSON6)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1 x 0.5 mm SOT891

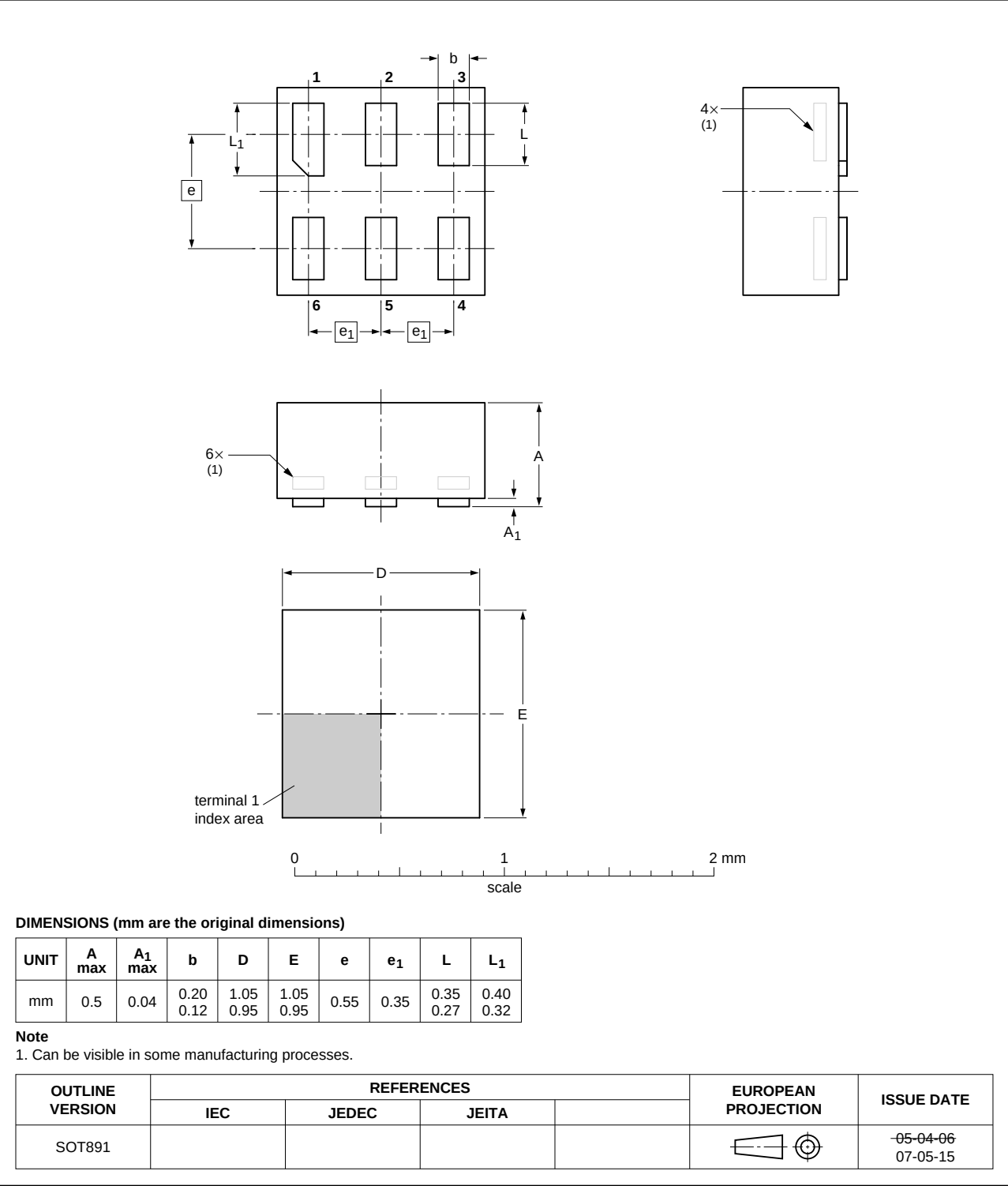


Fig 15. Package outline SOT891 (XSON6)

XSON6: extremely thin small outline package; no leads;
6 terminals; body 0.9 x 1.0 x 0.35 mm

SOT1115

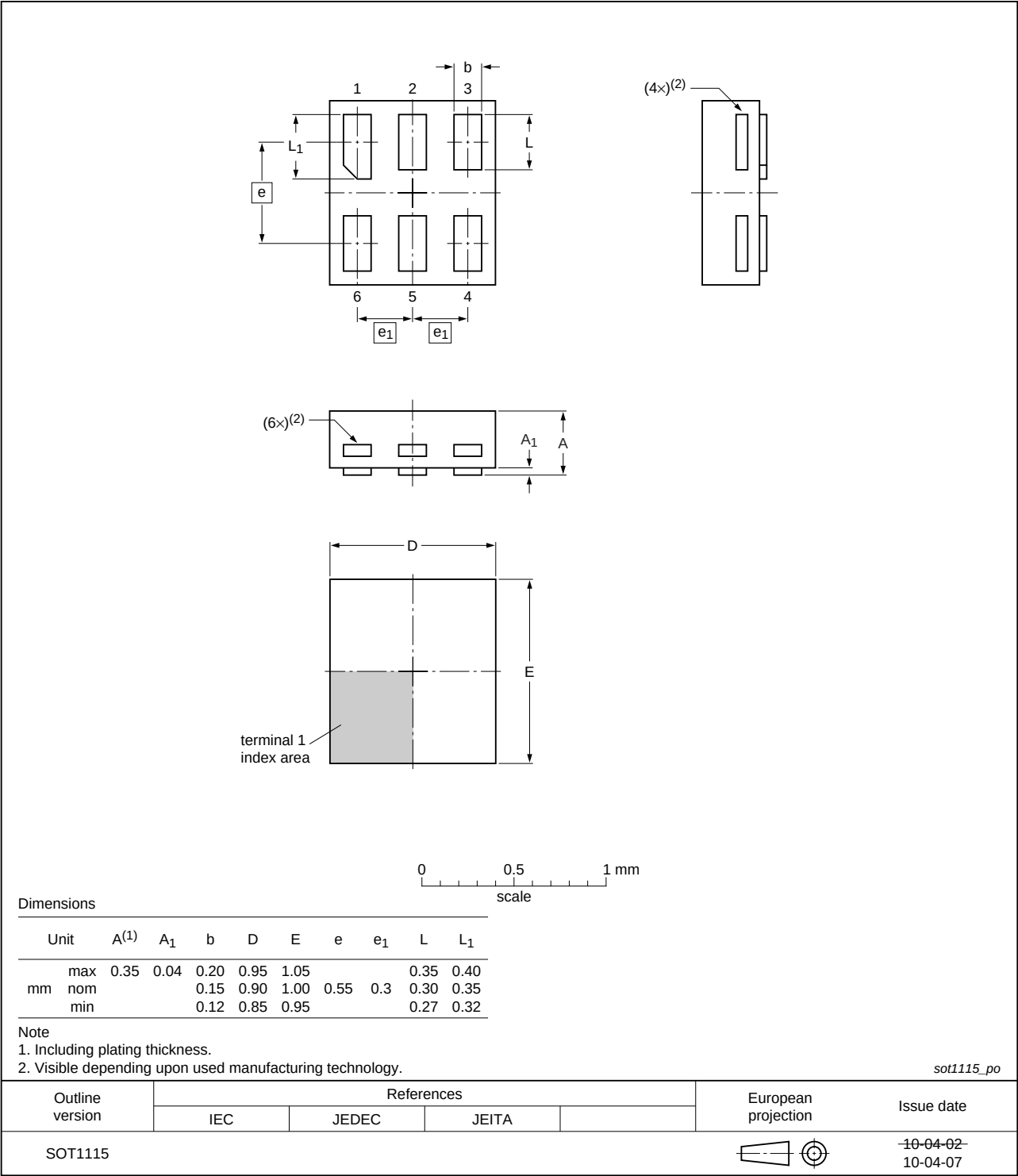
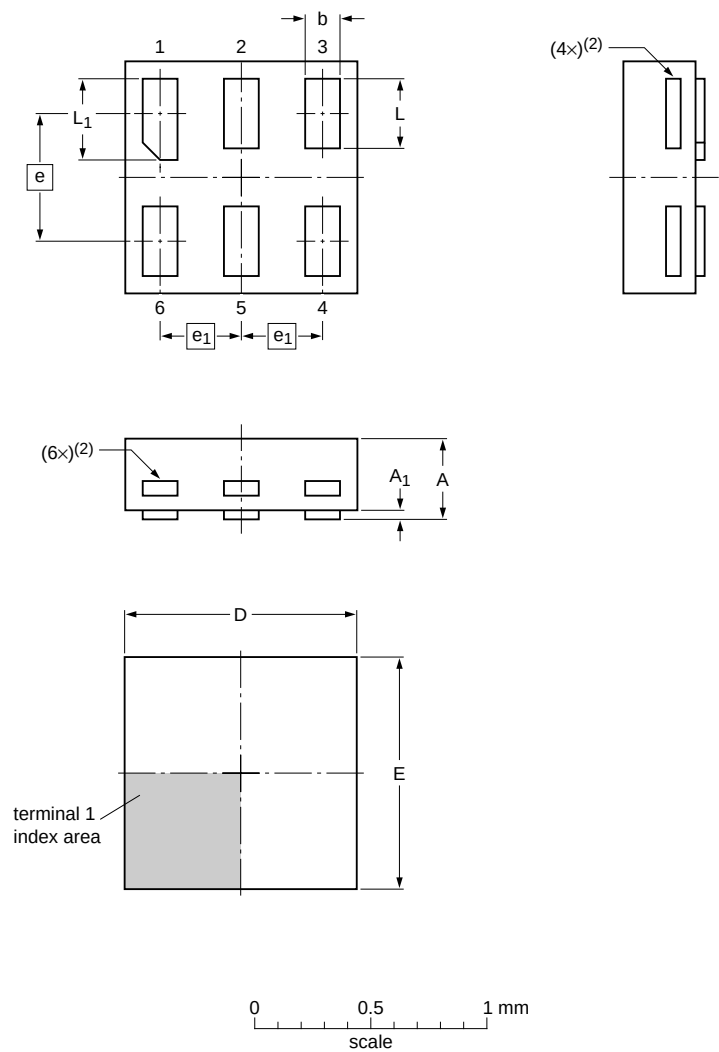


Fig 16. Package outline SOT1115 (XSON6)

XSON6: extremely thin small outline package; no leads;
6 terminals; body 1.0 x 1.0 x 0.35 mm

SOT1202



Dimensions

Unit	A ⁽¹⁾	A ₁	b	D	E	e	e ₁	L	L ₁
mm	max	0.35	0.04	0.20	1.05	1.05		0.35	0.40
	nom			0.15	1.00	1.00	0.55	0.30	0.35
	min			0.12	0.95	0.95		0.27	0.32

Note

- 1. Including plating thickness.
- 2. Visible depending upon used manufacturing technology.

sot1202_po

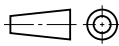
Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1202						-10-04-02- 10-04-06

Fig 17. Package outline SOT1202 (XSON6)

16. Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

17. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AUP2GU04 v.5	20131011	Product data sheet	-	74AUP2GU04 v.4
Modifications:	• Package outline drawing of SOT886 (Figure 14) modified.			
74AUP2GU04 v.4	20111207	Product data sheet	-	74AUP2GU04 v.3
Modifications:	• Legal pages updated.			
74AUP2GU04 v.3	20101110	Product data sheet	-	74AUP2GU04 v.2
74AUP2GU04 v.2	20090703	Product data sheet	-	74AUP2GU04 v.1
74AUP2GU04 v.1	20061215	Product data sheet	-	-

18. Legal information

18.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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